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1 Introduction

As mentioned in Deliverable D8.2.1 (Initial Dissemination Plan), the dissemination activities for THERMINATOR are performed in Task T8.2 that runs for all the duration of the project. The target of this Task is to spread Europe-wide the knowledge gained during the execution of the THERMINATOR project.

The approach that has been taken in the first 18 months for achieving this goal consisted of three types of actions:

1. Publication of scientific articles in books, technical journals, conference and workshop proceedings with international scope and visibility.
2. Promotion of the R&D effort performed by the THERMINATOR Consortium through press releases in international, national and local/regional newspapers and magazines, as well as in international, national and regional/local events such as fairs and exhibits, emphasizing the fundamental role that EU funding has on the development of nanoelectronics research in Europe.
3. Set-up and maintenance of the THERMINATOR web-site, which will make available to the European design community, documents and reports describing technical and scientific achievements, information on training options, scientific publications, a mailing-list and a mechanism to create awareness of the THERMINATOR public events.

Since the dissemination results that the THERMINATOR consortium achieved in the first 18 months are extremely satisfactory, (23 papers published in international journals and conferences) as witnessed also in Deliverable D8.2.2 (first report on dissemination activities), we plan to continue in the same direction and implement the same actions for disseminating the results we will obtain till the end of the project.

In particular, as mentioned in the deliverable D8.2.1, a specific Task is dedicated to the web site creation, updating and maintenance (Task T8.1). Details are given in Deliverable D8.1.1.

The dissemination activities regarding publication of articles and papers, as well as additional advertisement initiatives such as participation to conferences, fairs and other public events, have been surveyed, on a partner-by-partner basis, in Deliverable D8.2.2 (M12) and the follow-up of these activities will be described in Deliverables D8.2.4 (M24) and D8.2.5 (M36). These activities complement the training actions that the partners undertake in the context of Task T8.3. The project, as expected, has produced and will generate a large amount of innovative, scientifically sound research results, which led and will lead to several publications. The scientific impact that the project has on the nanoelectronics community is highlighted by the number and quality of the papers published jointly by the partners. In this document, as already done in the “initial dissemination plan”, we report also a list of the most common international conferences and events, strictly correlated to the technical topics covered in the THERMINATOR project, that the partners of the consortium participated or plan to participate at, in order to present to a broad audience the objectives and the results obtained during and at the end of the project.

2 Dissemination Strategy

The dissemination strategy that the THERMINATOR Consortium followed during the first 18 months, and that will be followed till the end of the project (as mentioned above and as described in D8.2.2), the obtained results are very promising) targets both internal and external audience. The internal audience is extremely important to enforce the collaboration within the THERMINATOR partners and to spread the gained knowledge within the consortium. The external audience includes the scientific community (either academic or industrial) and the nanoelectronics market at large. Various dissemination media and/or events have been and will be considered according to the various targeted audiences. The following table lists the type of audience we target in the project:

Media	Audience
International conferences and workshops	Public
International journals	Public
Mailing lists	Internal
Internal tutorials and meetings	Internal
Bachelor/Master/PhD courses	Public
IEEE e-learning platform courses	Public

2.1 International Conferences and Workshops

THERMINATOR partners have targeted and will target several international conferences and workshops for publishing technical papers, organizing special sessions and personally attending presentations, panels and round tables.

Conference publications are extremely important for disseminating the research outcomes of the project. In the first year of the project the THERMINATOR partners have in fact published 18 papers on research topics related to the THERMINATOR project. In addition to the publications, the members of the Consortium are and will be also actively present in many scientific committees of conferences and scientific networks. This is another valuable set of entry points for disseminating the THERMINATOR results as well as to organize specific session on the related topics.

The following is a list of conferences and workshops that THERMINATOR partners plan to attend or to send technical contributions

- **THERMINIC (International Workshop on Thermal Investigation of ICs and Systems)**

THERMINIC Workshops are a series of events to discuss the essential thermal questions of microelectronic microstructures and electronic parts in general.

In particular, THERMINIC 2011 will address in addition to the "traditional" thermal management problems, also stress and thermal-stress-related-reliability issues, both in micro- and opto-electronics fields. These issues, including various nanotechnology applications, are of significant importance and of high interest to the engineering community engaged in the field of thermal phenomena in "high-tech" systems.

<http://cmp.imag.fr/conferences/therminic/>

In THERMINIC 2011, THERMINATOR partners will organize two special Sessions dedicated to disseminate the project results to the thermal management community.

- **ESSCIRC (European Solid State Circuits Conference)**

The aim of the ESSCIRC conference is to provide an annual European forum for the presentation and discussion of recent advances in solid-state circuits. ESSCIRC and its sister conference ESSDERC, which deals with solid-state devices and technologies, are governed by a single Steering Committee. The increasing level of integration for system-on-chip (SoC) design made available by advances in silicon technology is stimulating more than ever before the need for deeper interaction among technologists, device experts, and circuit and system designers.

<http://www.esscirc2011.org/>
- **ESSDERC (European Solid-State Device Research Conference)**

The aim of the ESSDERC conference is to provide an annual European forum for the presentation and discussion of recent advances in solid-state devices and technologies. ESSDERC and its sister conference ESSCIRC, which deals with solid-state circuits, are governed by a single Steering Committee. The increasing level of integration for system-on-chip design made available by advances in silicon technology is stimulating more than ever before the need for deeper interaction among technologists, device experts, and circuit and system designers.

<http://www.essderc2011.org/>
- **IEDM (International Electron Devices Meeting)**

Over the last 56 years, the IEEE/IEDM has been the world's main forum for reporting breakthroughs in technology, design, manufacturing, physics and the modeling of semiconductors and other electronic devices. Topics range from deep submicron CMOS transistors and memories to novel displays and imagers, from compound semiconductor materials to nanotechnology devices and architectures, from micro-machined devices to smart-power technologies, etc.

<http://www.his.com/~iedm/>
- **VLSI (Symposium on VLSI Technology)**

For many reasons, the combined technology and circuits meetings have remained linked for the past years to provide opportunities for technology people and circuit and system designers to interact with each other. The presentation of high-quality papers has made it possible for attendees to learn about new directions in the development of VLSI technology.

<http://www.vlsisymposium.org/>
- **ISSCC (International Solid State Circuits Conference)**

The International Solid-State Circuits Conference is the foremost forum for presentation of advances in solid-state circuits and systems-on-a-chip. The Conference offers a unique opportunity for engineers working at the cutting edge of IC design and use to network with leading experts.

<http://www.isscc.org/isscc/index.htm>

- **DAC (Design Automation Conference)**

DAC is the world's leading technical conference and tradeshow, covering the latest trends in electronic design and design automation. DAC is where the IC Design and EDA ecosystem learns, networks, and does business — where critical industry issues are faced and solutions presented.

<http://www.dac.com>
- **DATE (Design Automation & Test in Europe)**

The DATE conference and exhibition is the main European event bringing together designers and design automation users, researchers and vendors, as well as specialists in the hardware and software design, test and manufacturing of electronic circuits and systems. It puts strong emphasis on ICs/SoCs, reconfigurable hardware and embedded systems, including embedded software.

<http://www.date-conference.com>
- **ISLPED (International Symposium on Low Power Electronics and Design)**

ISLPED is the premier forum for presentation of recent advances in all aspects of low power design and technologies, ranging from process and circuit technologies, to simulation and synthesis tools, to system level design and optimization.

<http://www.islped.org/>
- **PATMOS (International Workshop on Power And Timing Modeling, Optimization and Simulation)**

The objective of the PATMOS workshop is to provide a forum to discuss and investigate the emerging problems in the design methodologies and CAD-tools for the new generation of IC technologies. A major emphasis of the technical program is on speed and low-power aspects with particular regard to modeling, characterization, design, and architectures.

<http://www.patmos-conf.org/>
- **GLS-VLSI (Great Lake Symposium on VLSI)**

GLS-VLSI is an international conference where original, unpublished papers, describing research in the general area of VLSI are solicited. Both theoretical and experimental research results are welcome.

<http://www.glsvlsi.org>
- **VLSI-SoC (International Conference on VLSI and System-on-Chip)**

VLSI-SoC is an international conference that explores the state-of-the-art and the new developments in the field of Very Large Scale Integration (VLSI), System-on-Chip (SoC) and their designs. The purpose of VLSI-SoC is to provide a forum to exchange ideas, and show industrial and research results in the fields of VLSI/ULSI Systems, SoC design, VLSI CAD and Microelectronic Design and Test.

<http://www.vlsi-soc.com/>
- **DSD (EUROMICRO Conference on Digital System Design)**

The Euromicro Conference on Digital System Design addresses all aspects of (embedded and high-performance) digital and mixed hardware/software system engineering, down to microarchitectures, digital circuits and VLSI techniques. It is a discussion forum for researchers and engineers working on state-of-the-art investigations, development and applications.

<http://www.dsdconf.org/>

- **GSA (Global Semiconductor Association)**

GSA & IET International Semiconductor Leadership Forum is the leading conference focused on European trends in semiconductor development and markets. Attendees come from Europe, Asia and the US and comprise professionals from fabless companies, industry suppliers and integrated device manufacturers, as well as executive leaders. The conference is focusing on leveraging and maximizing European expertise in analog/mixed-signal, wireless, low-power applications and quality/reliability to access the emerging markets for silicon growth in areas that include smart cards, power electronics and home networking worldwide.

<http://www.gsaietsemiconductorforum.com>
- **ASP-DAC / EDS-Fair**

ASP-DAC is the largest annual international conference on VLSI design automation in Asia and South Pacific region, one of the most active regions of design and fabrication of silicon chips in the world. The conference aims at providing the Asian and South Pacific CAD/DA and Design community with opportunities of presenting recent advances and with forums for future directions in technologies related to Electronic Design Automation (EDA). The format of the meeting intends to cultivate and promote an instructive and productive interchange of ideas among EDA researchers/developers and system/circuit/device designers. All scientists, engineers, and students who are interested in theoretical and practical aspects of VLSI design and design automation are welcome to ASP-DAC.

<http://www.aspdac.com/>
- **MUGM (MunEDA User Group Meeting)**

The MUGM MunEDA User Group Meeting is an open conference and workshop for MunEDA users and research partners taking place annually in Munich / Germany. At MUGM invited papers will be presented about research, development, design flow implementation and application of methodologies for enhanced analysis, modeling, optimization and verification of analog, mixed-signal and digital circuits on block- and transistor level. Furthermore, MUGM also serves as potential platform for presentations and publications from MunEDA project partners such as in THERMINATOR.

<http://www.muneda.com/MUGM>
- **ULIS (Ultimate Integration on Silicon)**

ULIS provides an open forum for the presentation and discussion of recent research in technology, physics, modelling, simulation and characterisation of advanced nanoscale silicon and silicon compatible devices in the More Moore, More than Moore and Beyond CMOS domains.

www.ulisconference.org/
- **SISPAD (International Conference on Simulation of Semiconductor Processes and Devices)**

SISPAD provides an international forum for presentation of leading-edge research and development results in the area of process and device simulation. SISPAD is held annually, with the location of the conference circulating among Asia, Europe, and the U.S., and is one of the longest running conferences devoted to technology computer-aided design (TCAD).

<http://www.sispad.org/sispad/sispadorg.html>

2.2 International Journals

THERMINATOR partners plan to publish technical papers on the most relevant international journals in order to maximize the prestige of the results obtained from THERMINATOR. In the first year of the project THERMINATOR partners have published 5 technical paper in some of the most important international journals.

Here we recall a list of the target journals:

- **JETCAS (IEEE Journal on Emerging and Selected Topics in Circuits and Systems)**

JETCAS is published quarterly and solicits, with particular emphasis on emerging areas, special issues on topics that cover the entire scope of the IEEE Circuits and Systems (CAS) Society, namely the theory, analysis, design, tools, and implementation of circuits and systems, spanning their theoretical foundations, applications, and architectures for signal and information processing.
<http://jetcas.polito.it/general.html>

- **TCAD (IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems)**

Manuscripts considered for publication should focus on algorithms, methods, techniques, and tools for the automated design of integrated circuits and systems, and on related areas. Submitted papers may be of a tutorial or research nature. Research papers must present original contributions and must show significant new material over descriptions or derivations available elsewhere. Tutorial papers should review the state-of-the-art in specific areas of CAD and, at the same time, present readers with key research perspectives and future challenges.
<http://tcad.polito.it/>

- **TVLSI (IEEE Transactions on Very Large Scale Integration (VLSI) Systems)**

Manuscripts should address all major aspects of the design and implementation of VLSI/ULSI and microelectronic systems. Topics of special interest include: systems specifications, design and partitioning, high performance computing and communication systems, neural networks, wafer-scale integration and multichip module systems and their applications.
<http://www.princeton.edu/~tvlsi/>

- **TCAS I (IEEE Transactions on Circuits and Systems - Part I: Regular Papers)**

The field of interest covers the area of pertinence of the Circuits and Systems Society (CAS), namely the theory, analysis, (computer aided) design, and practical implementation of circuits, and the application of circuit theoretic techniques to systems and to signal processing.
<http://cas1.polito.it/>

- **TCAS II (IEEE Transactions on Circuits and Systems - Part II: Express Briefs)**

Its primary goal is *rapid dissemination* of original, timely and significant contributions to the research community. The papers are expected to contain new results, ideas, or innovations that advance significantly the state-of-the-art circuits and systems.
<http://cas2.polito.it/>

- **TC (IEEE Transactions on Computers)**
TC publishes papers, brief contributions, and comments on research in areas of current interest to the readers. These areas include, but are not limited to, the following: a) computer organizations and architectures; b) operating systems, software systems, and communication protocols; c) real-time systems and embedded systems; d) digital devices, computer components, and interconnection networks; e) specification, design, prototyping, and testing methods and tools; f) performance, fault tolerance, reliability, security, and testability; g) case studies and experimental and theoretical evaluations; and h) new and important applications and trends.
<http://www.computer.org/portal/web/tc>
- **TR (IEEE Transactions on Reliability)**
TR is a refereed journal for the reliability and allied disciplines including but not limited to maintainability, physics of failure, life testing, prognostics, design and manufacture for reliability, systems of systems, network availability, mission success, warranty, safety, and various measures of effectiveness. Topics eligible for publications range *from hardware to software, from materials to systems, from consumer & industrial devices to manufacturing plants, from individual items to networks, from techniques for making things better to ways of predicting/measuring behavior in the field.*
<http://ieeexplore.ieee.org/xpl/RecentIssue.jsp?punumber=24>
- **TED (IEEE Transaction on Electron Devices)**
TED publishes original and significant contributions relating to the theory, modeling, design, performance and reliability of electron and ion integrated circuit devices and interconnects, involving insulators, metals, organic materials, micro-plasmas, semiconductors, quantum-effect structures, vacuum devices, and emerging materials with applications in bioelectronics, biomedical electronics, computation, communications, displays, microelectromechanics, imaging, micro-actuators, nanotechnology, optoelectronics, photovoltaics, power ICs and micro-sensors.
<http://www.ieee.org/portal/pages/society/eds/pubs/ted/ted.html>

2.3 Internal Tutorials and Meetings

THERMINATOR cooperation among the partners is enforced by organizing internal technical or plenary meetings, conference calls and tutorials. These meetings are organized in order to support good functioning and sharing of information and vision over the THERMINATOR work during the several phases of the project development.

2.4 Bachelor/Master/PhD courses

Particular attention has been and will be paid to create awareness also “from the bottom” on the design methodologies under development in THERMINATOR and in particular on the thermal issues that designers have to deal with when designing modern nanoelectronic devices. To this purpose, some academic courses on embedded systems design, low-power design, microelectronics for SoCs and microelectronic technology have included and will include presentations of specific topics and development of project assignments/master thesis based on the THERMINATOR research topics.

2.5 IEEE e-learning platform courses

Thanks to the links that some partners have with the IEEE society, the consortium had the opportunity of putting online, by means of the IEEE website, courses targeting THERMINATOR research topics.

This is a very effective instrument for improving the dissemination activities, in fact, as reported on the IEEE website, the IEEE eLearning Library offers advanced technology content only IEEE can provide. The convenient learning system delivers nearly 200 courses in core and emerging technologies, providing professionals, faculty and students across academic institutions, corporations and government agencies a better way to learn.

IEEE eLearning Library selects the best educational courses from IEEE conferences and workshops around the world and delivers them in engaging, instructional and interactive online courses.

Researchers can use IEEE eLearning Library to easily stay abreast of the latest developments in related technologies, creating greater synergy with other product and R&D teams and enabling your team to take advantage of greater market opportunities.

3 Conclusion

Following the extremely good results that the Consortium achieved after the first year of the project (18 conference papers, 5 journal paper, several courses, seminars and invited speeches), the same dissemination guidelines will be used also in the future of the project by all the THERMINATOR partners.